ABSTRACT

A semiconductor chip package includes a dielectric layer having an attachment portion and an offset portion, off-set downwardly from the attachment portion. A semiconductor chip is mounted to the attachment portion, typically on a bottom or downwardly-facing surface thereof. Terminal structures carried by the offset portion can be bonded to contact pads of a circuit panel by small lands or masses of solder or other bonding material. The package can be thin, and may occupy only a small area of the circuit panel.